



DICING SERVICE APPLICATION DATA SHEET

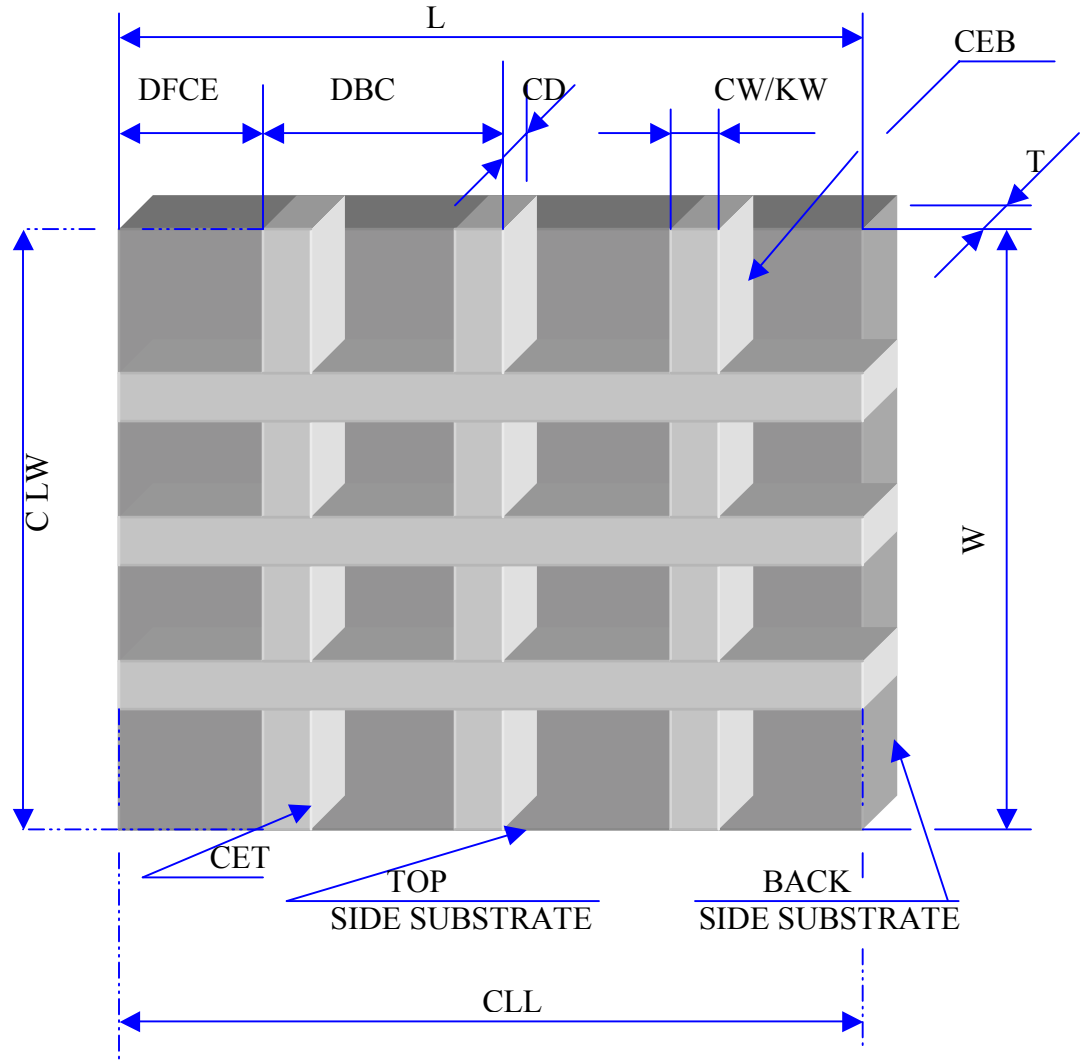
Abbreviation	Size (" /mm)	Tolerance " / μ m
L		
CLL		
W		
CLW		
DFCE		
DBC		
CD		
CW/KW		
T		
CET		
CEB		

SUBSTRATE MATERIAL TYPE:

SPINDLE SPEED (R.P.M.):

FEED RATE-TABLE OR SPINDLE SPEED (INCH OR MILIMMETER PER SECOND)

Mounting method



TERMINOLOGY

- L**-Length of substrate
- CLL**-Cut length on length of substrate
- W**-width of substrate
- CLW**-Cut length on width of substrate
- DFCE**-Distance of first cut from the edge of substrate
- DBC**- Distance between the cuts (Index)
- CD**- Cut depth
- CW/KW**- Cut width (Kerf width)
- T**-Thickness of substrate
- CET**- Chipping on the edges of cut on top side substrate
- CEB**- Chipping on the edges of cut on back side substrate